

Quad 2-Input AND Gate

With 5V-Tolerant Inputs

The MC74LVX08 is an advanced high speed CMOS 2-input AND gate. The inputs tolerate voltages up to 7V, allowing the interface of 5V systems to 3V systems.

- High Speed: $t_{PD} = 4.8\text{ns}$ (Typ) at $V_{CC} = 3.3\text{V}$
- Low Power Dissipation: $I_{CC} = 2\mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: $V_{OLP} = 0.5\text{V}$ (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300mA
- ESD Performance: HBM > 2000V; Machine Model > 200V

MC74LVX08

LVX

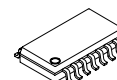
LOW-VOLTAGE CMOS



D SUFFIX
14-LEAD SOIC PACKAGE
CASE 751A-03



DT SUFFIX
14-LEAD TSSOP PACKAGE
CASE 948G-01



M SUFFIX
14-LEAD SOIC EIAJ PACKAGE
CASE 965-01

PIN NAMES

Pins	Function
An, Bn On	Data Inputs Outputs

MC74LVX08

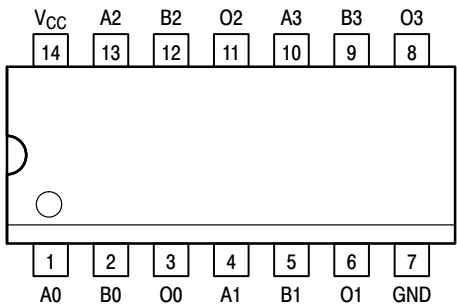


Figure 1. 14-Lead Pinout (Top View)

FUNCTION TABLE

INPUTS		OUTPUTS
An	Bn	On
L	L	L
L	H	L
H	L	L
H	H	H

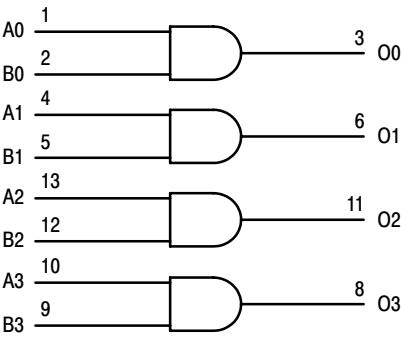


Figure 2. Figure 1. Logic Diagram

MC74LVX08

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	−0.5 to +7.0	V
V _{in}	DC Input Voltage	−0.5 to +7.0	V
V _{out}	DC Output Voltage	−0.5 to V _{CC} +0.5	V
I _{IK}	Input Diode Current	−20	mA
I _{OK}	Output Diode Current	±20	mA
I _{out}	DC Output Current, per Pin	±25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±50	mA
P _D	Power Dissipation	180	mW
T _{stg}	Storage Temperature	−65 to +150	°C

* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	3.6	V
V _{in}	DC Input Voltage	0	5.5	V
V _{out}	DC Output Voltage	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	−40	+85	°C
Δt/ΔV	Input Rise and Fall Time	0	100	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CC} V	T _A = 25°C			T _A = −40 to 85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	High–Level Input Voltage		2.0 3.0 3.6	1.5 2.0 2.4			1.5 2.0 2.4		V
V _{IL}	Low–Level Input Voltage		2.0 3.0 3.6			0.5 0.8 0.8		0.5 0.8 0.8	V
V _{OH}	High–Level Output Voltage (V _{in} = V _{IH} or V _{IL})	I _{OH} = −50μA I _{OH} = −50μA I _{OH} = −4mA	2.0 3.0 3.0	1.9 2.9 2.58	2.0 3.0		1.9 2.9 2.48		V
V _{OL}	Low–Level Output Voltage (V _{in} = V _{IH} or V _{IL})	I _{OL} = 50μA I _{OL} = 50μA I _{OL} = 4mA	2.0 3.0 3.0		0.0 0.0	0.1 0.1 0.36		0.1 0.1 0.44	V
I _{in}	Input Leakage Current	V _{in} = 5.5V or GND	3.6			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	V _{in} = V _{CC} or GND	3.6			2.0		20.0	μA

MC74LVX08

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0\text{ns}$)

Symbol	Parameter	Test Conditions	$T_A = 25^\circ\text{C}$			$T_A = -40 \text{ to } 85^\circ\text{C}$		Unit
			Min	Typ	Max	Min	Max	
t_{PLH} , t_{PHL}	Propagation Delay, Input to Output	$V_{CC} = 2.7\text{V}$ $C_L = 15\text{pF}$ $C_L = 50\text{pF}$		6.3 8.8	11.4 14.9	1.0 1.0	13.5 17.0	ns
		$V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 15\text{pF}$ $C_L = 50\text{pF}$		4.8 7.3	7.1 10.6	1.0 1.0	8.5 12.0	
t_{OSHL} , t_{OSLH}	Output-to-Output Skew (Note NO TAG)	$V_{CC} = 2.7\text{V}$ $C_L = 50\text{pF}$ $V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$			1.5 1.5		1.5 1.5	ns

- Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	$T_A = 25^\circ\text{C}$			$T_A = -40 \text{ to } 85^\circ\text{C}$		Unit
		Min	Typ	Max	Min	Max	
C_{in}	Input Capacitance		4	10		10	pF
C_{PD}	Power Dissipation Capacitance (Note NO TAG)		18				pF

- C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}/4$ (per gate). C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

NOISE CHARACTERISTICS (Input $t_r = t_f = 3.0\text{ns}$, $C_L = 50\text{pF}$, $V_{CC} = 3.3\text{V}$, Measured in SOIC Package)

Symbol	Characteristic	$T_A = 25^\circ\text{C}$		Unit
		Typ	Max	
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	0.3	0.5	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	-0.3	-0.5	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		2.0	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		0.8	V

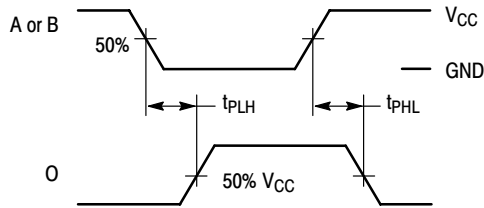
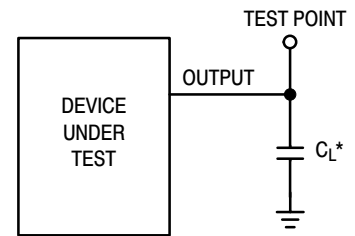


Figure 3. Switching Waveforms



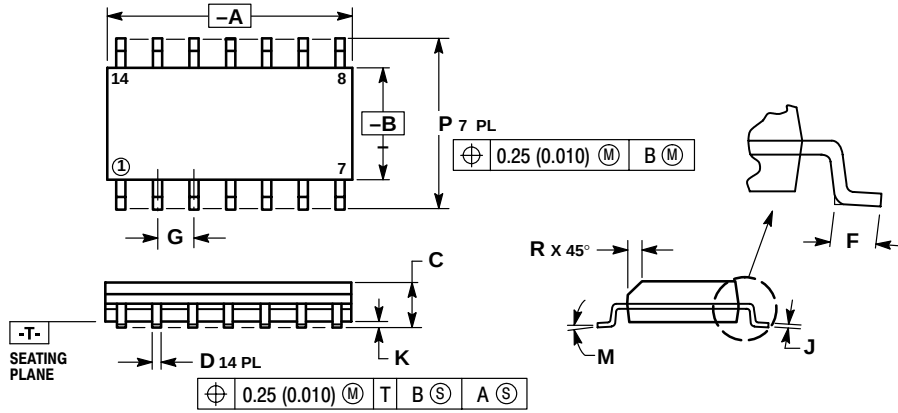
*Includes all probe and jig capacitance

Figure 4. Test Circuit

MC74LVX08

OUTLINE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751A-03
ISSUE F



NOTES:

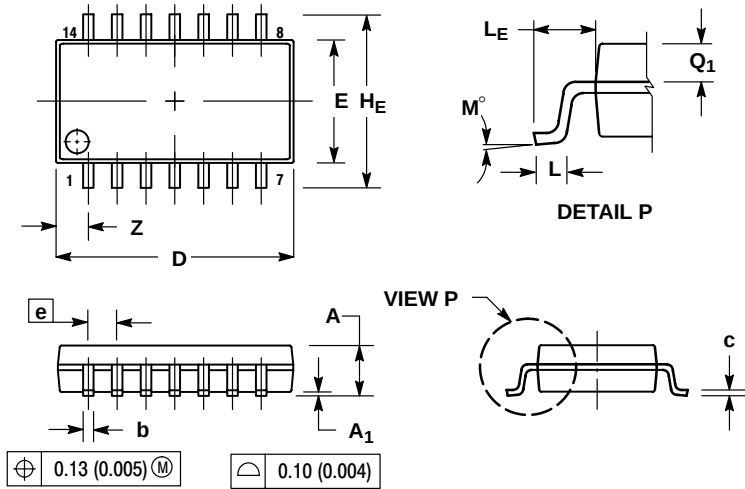
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

MC74LVX08

OUTLINE DIMENSIONS

M SUFFIX
PLASTIC SOIC EIAJ PACKAGE
CASE 965-01
ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

OUTLINE DIMENSIONS

Technical drawing of a rectangular component with various views and dimensions.

Top View: Shows a rectangular component with dimensions A and B . The top edge has 14 pins, labeled 14 and 8. The bottom edge has 7 pins, labeled 7. The left edge has a dimension L and a feature $2X L/2$. The right edge has a dimension B and a feature $-U-$. The bottom edge has a dimension A and a feature $-V-$. The top edge has a feature $14X K REF$ and a dimension $0.10 (0.004) \text{ (M)}$. The left edge has a feature $0.15 (0.006) T U \text{ (S)}$. The bottom edge has a feature $0.15 (0.006) T U \text{ (S)}$. The top edge has a feature $14X K REF$ and a dimension $0.10 (0.004) \text{ (M)}$. The left edge has a feature $0.15 (0.006) T U \text{ (S)}$. The bottom edge has a feature $0.15 (0.006) T U \text{ (S)}$.

Side View: Shows the component from the side, with dimensions C and D . The top edge has a dimension C and a feature $14X K REF$. The bottom edge has a dimension D and a feature $14X K REF$. The top edge has a feature $14X K REF$ and a dimension $0.10 (0.004) \text{ (M)}$. The left edge has a feature $0.15 (0.006) T U \text{ (S)}$. The bottom edge has a feature $0.15 (0.006) T U \text{ (S)}$.

Detail E: Shows a detail of the component, with dimensions N and M . The top edge has a dimension N and a feature $0.25 (0.010)$. The bottom edge has a dimension M and a feature $0.25 (0.010)$. The top edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$. The bottom edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$.

Section N-N: Shows a cross-section of the component, with dimensions J and $J1$. The top edge has a dimension J and a feature $0.25 (0.010)$. The bottom edge has a dimension $J1$ and a feature $0.25 (0.010)$. The top edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$. The bottom edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$.

Detail E: Shows a detail of the component, with dimensions K and $K1$. The top edge has a dimension K and a feature $0.25 (0.010)$. The bottom edge has a dimension $K1$ and a feature $0.25 (0.010)$. The top edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$. The bottom edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$.

Detail E: Shows a detail of the component, with dimensions H and G . The top edge has a dimension H and a feature $0.25 (0.010)$. The bottom edge has a dimension G and a feature $0.25 (0.010)$. The top edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$. The bottom edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$.

Detail E: Shows a detail of the component, with dimensions H and G . The top edge has a dimension H and a feature $0.25 (0.010)$. The bottom edge has a dimension G and a feature $0.25 (0.010)$. The top edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$. The bottom edge has a feature $0.25 (0.010)$ and a dimension $0.25 (0.010)$.

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	----	1.20	----	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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